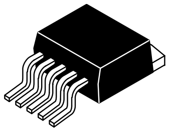
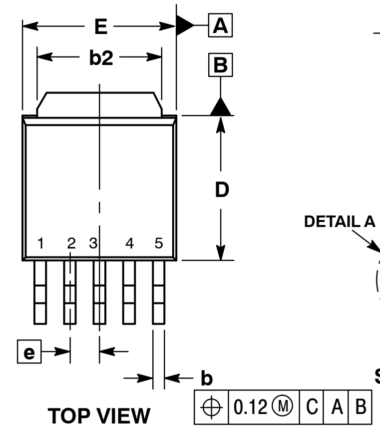


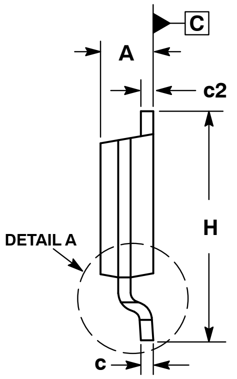
SCALE 1:1

DPAK−5 (TO−252, 5 LEAD)
CASE 369AE
ISSUE A

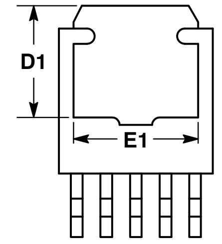
DATE 14 AUG 2013



TOP VIEW



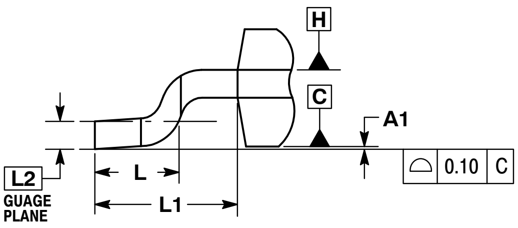
SIDE VIEW



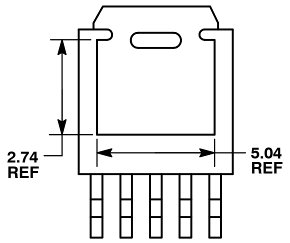
BOTTOM VIEW

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. THERMAL PAD CONTOUR OPTIONAL, WITHIN DIMENSIONS SHOWN.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15mm PER SIDE.
5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.

DIM	MILLIMETERS	
	MIN	**MAX**
A	2.10	2.50
A1	0.00	0.13
b	0.40	0.60
b2	5.14	5.54
c	0.40	0.60
c2	0.40	0.60
D	5.40	6.30
D1	4.80	5.10
E	6.35	6.80
E1	4.75	5.05
e	1.27 BSC	
H	9.50	10.20
L	1.39	1.78
L1	2.50	2.90
L2	0.51 BSC	



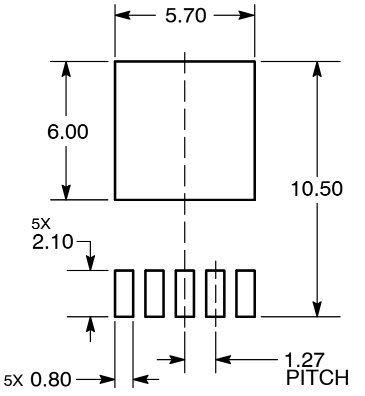
DETAIL A



BOTTOM VIEW

ALTERNATE CONSTRUCTION

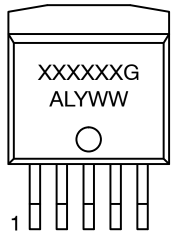
RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



A = Assembly Location
L = Wafer Lot
Y = Year
WW = Work Week
G = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking.

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DESCRIPTION:	**DPAK−5 (TO−252, 5 LEAD)**	**PAGE 1 OF 1**